

# SGM7228 Low Cost, High Speed USB 2.0 (480Mbps) DPDT Analog Switch

#### **GENERAL DESCRIPTION**

The SGM7228 is a high-speed, low-power double-pole/double-throw (DPDT) analog switch that operates from a single 1.8V to 4.3V power supply.

SGM7228 is designed for the switching of high-speed USB 2.0 signals in handset and consumer applications, such as cell phones, digital cameras, and notebooks with hubs or controllers with limited USB I/Os.

The SGM7228 has low bit-to-bit skew and high channel-to-channel noise isolation, and is compatible with various standards, such as high-speed USB 2.0 (480 Mbps). Each switch is bidirectional and offers little or no attenuation of the high-speed signals at the outputs. Its bandwidth is wide enough to pass high-speed USB 2.0 differential signals (480 Mb/s) with good signal integrity.

The SGM7228 contains special circuitry on the D+/D-pins which allows the device to withstand a  $V_{\text{BUS}}$  short to D+ or D- when the USB devices are either powered off or powered on.

SGM7228 is available TQFN-1.8×1.4-10L package. It operates over an ambient temperature range of -40°C to +85°C.

## **APPLICATIONS**

Route Signals for USB 2.0
MP3 and Other Personal Media Players
Digital Cameras and Camcorders
Portable Instrumentation
Set-Top Box
PDAs

#### **FEATURES**

- Low Cost
- R<sub>ON</sub> is Typically 6Ω at 3.0V
- Low Bit-to-Bit Skew: 50ps (TYP)
- Voltage Operation: 1.8V to 4.3V
- Fast Switching Times:

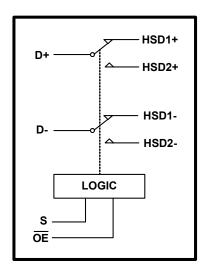
t<sub>ON</sub> 10ns t<sub>OFF</sub> 22ns

- Low Crosstalk: -40dB at 250MHz
- Power-Off Protection when V<sub>+</sub> = 0V,

D+/D- Pins can Tolerate up to 5.25V

- High Off-Isolation: -35dB at 250MHz
- Rail-to-Rail Input and Output Operation
- Break-Before-Make Switching
- Extended Industrial Temperature Range: -40°C to +85°C
- Small Package: TQFN-1.8×1.4-10L

### **BLOCK DIAGRAM**



### PACKAGE/ORDERING INFORMATION

MODEL	PIN- PACKAGE	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKAGE OPTION
SGM7228	TQFN-1.8×1.4-10L	-40℃ to +85℃	SGM7228YWQ10G/TR	7228	Tape and Reel, 3000

#### **ABSOLUTE MAXIMUM RATINGS**

$V_{+}$ to GND	Storage Temperature Range65°C to +150°C
Analog, Digital voltage range0.3V to $(V_+)$ + 0.3V	Lead Temperature (soldering, 10s)260°C
Continuous Current HSDn or Dn±100mA Peak Current HSDn or Dn±150mA	ESD Susceptibility
Operating Temperature Range40°C to +85°C	HBM4000V
	MM400V
Junction Temperature	

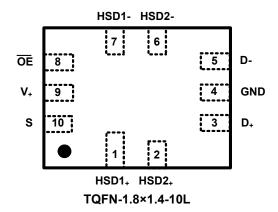
NOTE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **CAUTION**

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

SGMICRO reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time. Please contact SGMICRO sales office to get the latest datasheet.

# PIN CONFIGURATION (TOP VIEW)



## **PIN DESCRIPTION**

PIN	NAME	FUNCTION
9	$V_{+}$	Power Supply
4	GND	Ground
10	S	Select Input
8	ŌE	Output Enable
1, 2	HSD1+, HSD2+	
7, 6	HSD1-, HSD2-	Data Ports
3, 5	D+, D-	

# **FUNCTION TABLE**

ŌE	s	HSD1+ HSD1-	HSD2+ HSD2-
0	0	ON	OFF
0	1	OFF	ON
1	×	OFF	OFF

Switches Shown For Logic "0" Input

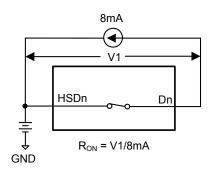
## **SGM7228**

# **ELECTRICAL CHARACTERISTICS**

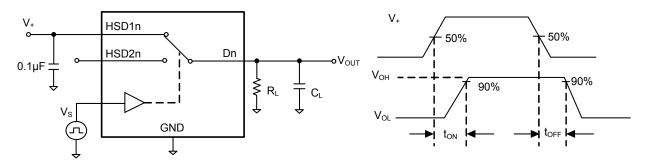
 $(V_{+} = +1.8V \text{ to } +4.3V, \text{ GND} = 0V, V_{IH} = +1.6V, V_{IL} = +0.5V, T_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}.$  Typical values are at  $V_{+} = +3.3V, T_{A} = +25^{\circ}\text{C}, \text{ unless otherwise noted.})$ 

PARAMETER	RAMETER SYMBOL CONDITIONS TEMP		MIN	TYP	MAX	UNITS	
ANALOG SWITCH							
Analog I/O Voltage (HSD1+, HSD1-, HSD2+, HSD2-)	V <sub>IS</sub>		-40°C to +85°C	0		V <sub>+</sub>	V
		$V_{+} = 3.0V$ , $V_{IS} = 0V$ to 0.4V, $I_{D} = 8mA$ ,	+25°C		6	10	
On-Resistance	R <sub>on</sub>	Test Circuit 1	-40°C to +85°C			10.5	Ω
On-Resistance Match Between	AD	$V_{+} = 3.0V$ , $V_{IS} = 0V$ to 0.4V, $I_{D} = 8mA$ ,	+25°C		0.15	0.6	
Channels	$\Delta R_{ON}$	Test Circuit 1	-40°C to +85°C			1.6	Ω
O. D. State of Flaters	5	$V_{+} = 3.0V$ , $V_{IS} = 0V$ to 1.0V, $I_{D} = 8mA$ ,	+25°C		1.5	2.0	
On-Resistance Flatness	$R_{FLAT(ON)}$	Test Circuit 1	-40°C to +85°C			2.6	Ω
Power Off Leakage Current (D+, D-)	l <sub>OFF</sub>	$V_{+} = 0V, V_{D} = 0V \text{ to } 3.6 \text{ V},$ $V_{S}, V_{\overline{OE}} = 0V \text{ or } 3.6 \text{ V}$	-40°C to +85°C			1	μA
Increase in I+ per Control Voltage	I <sub>CCT</sub>	$V_{+} = 3.6V, V_{S} \text{ or } V_{\overline{OE}} = 2.6 \text{ V}$	-40°C to +85°C			5	μA
Source Off Leakage Current	I <sub>HSD2(OFF)</sub> I <sub>HSD1(OFF)</sub>	$V_{+} = 3.6V, V_{IS} = 3.3V/0.3V,$ $V_{D} = 0.3V/3.3V$	-40°C to +85°C			1	μA
Channel On Leakage Current	I <sub>HSD2(ON)</sub> , I <sub>HSD1(ON)</sub>	$V_{+} = 3.6V, V_{IS} = 3.3V/0.3V,$ $V_{D} = 3.3V/0.3V$ or floating	-40°C to +85°C			1	μA
DIGITAL INPUTS							
Input High Voltage	V <sub>IH</sub>		-40°C to +85°C	1.6			V
Input Low Voltage	V <sub>IL</sub>		-40°C to +85°C			0.5	V
Input Leakage Current	I <sub>IN</sub>	$V_{+} = 3.0V, V_{S}, V_{\overline{OE}} = 0V \text{ or } V_{+}$	-40°C to +85°C			1	μA
DYNAMIC CHARACTERISTICS			ı			1	
Turn-On Time	t <sub>on</sub>	$V_{IS} = 0.8V$ , $R_L = 50\Omega$ , $C_L = 10pF$ ,	+25℃		10		ns
Turn-Off Time	t <sub>OFF</sub>	Test Circuit 2	+25℃		22		ns
Break-Before-Make Time Delay	t <sub>D</sub>	$V_{IS}$ = 0.8V, $R_L$ = 50 $\Omega$ , $C_L$ = 10pF, Test Circuit 3	+25°C		4		ns
Propagation Delay	t <sub>PD</sub>	$R_L = 50\Omega$ , $C_L = 10pF$	+25℃		0.3		ns
Off Isolation	O <sub>ISO</sub>	Signal = 0dBm, $R_L$ = 50 $\Omega$ , f = 250MHz, Test Circuit 4			-35		dB
Channel-to-Channel Crosstalk	X <sub>TALK</sub>	Signal = 0dBm, $R_L$ = 50 $\Omega$ , f = 250MHz, Test Circuit 5	+25°C		-40		dB
-3dB Bandwidth	BW	Signal = 0dBm, $R_L$ = 50 $\Omega$ , $C_L$ = 5pF Test Circuit 6	+25°C		550		MHz
Channel-to-Channel Skew	t <sub>skew</sub>	$R_L = 50\Omega, C_L = 10pF$	+25°C		0.05		ns
Charge Injection Select Input to Common I/O	Q	$V_G = GND, C_L = 1.0nF, R_G = 0\Omega,$ $Q = C_L \times V_{OUT}, Test Circuit 7$	+25°C		11		pC
HSD+, HSD-, D+, D- ON Capacitance	C <sub>on</sub>		+25°C		7		pF
POWER REQUIREMENTS							
Power Supply Range	V <sub>+</sub>		-40°C to +85°C	1.8		4.3	V
Power Supply Current	I <sub>+</sub>	$V_{+} = 3.0V, V_{S}, V_{\overline{OE}} = 0V \text{ or } V_{+}$	-40°C to +85°C			1	μA

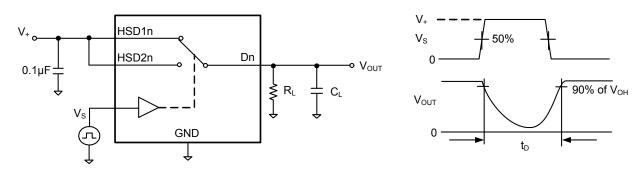
# **TEST CIRCUITS**



**Test Circuit 1. On Resistance** 

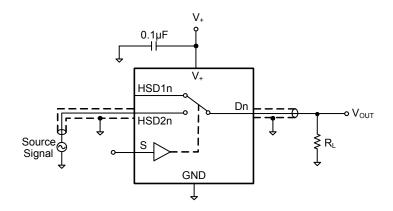


Test Circuit 2. Switching Times ( $t_{\text{ON}}$ ,  $t_{\text{OFF}}$ )

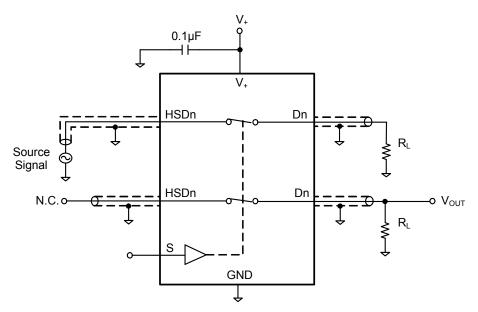


Test Circuit 3. Break-Before-Make Time (t<sub>D</sub>)

# **TEST CIRCUITS (Cont.)**



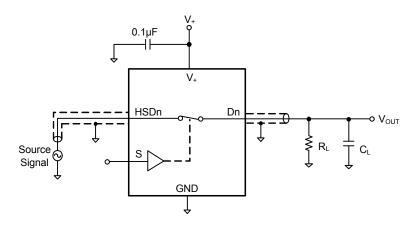
**Test Circuit 4. Off Isolation** 



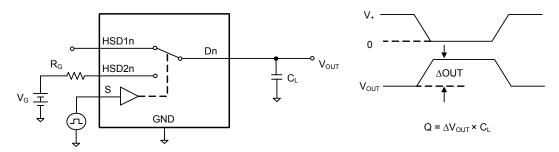
Channel To Channel Crosstalk = -20  $\times$  log  $\frac{V_{\text{HSDn}}}{V_{\text{OUT}}}$ 

Test Circuit 5. Channel-to-Channel Crosstalk

# **TEST CIRCUITS (Cont.)**



Test Circuit 6. -3dB Bandwidth



Test Circuit 7. Charge Injection (Q)

### SGM7228

### APPLICATION NOTES:

## Meeting USB 2.0 V<sub>BUS</sub> Short Requirements

In section 7.1.1 of the USB 2.0 specification, it notes that USB devices must be able to withstand a  $V_{\text{BUS}}$  short to D+ or D- when the USB devices is either powered off or powered on The SGM7228 can be successfully configured to meet both these requirements.

#### **Power-Off Protection**

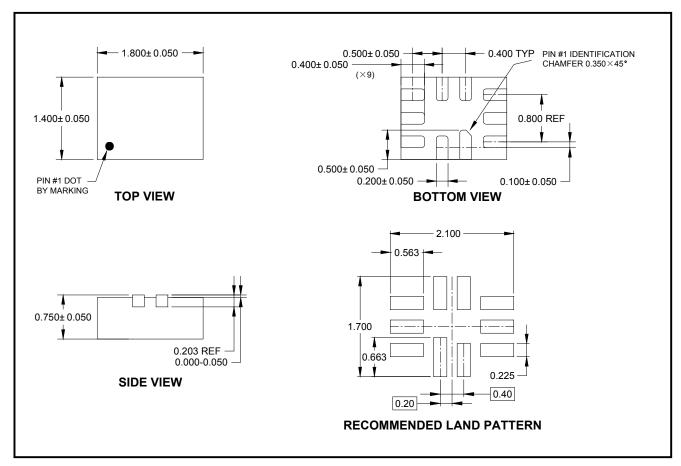
For a  $V_{\text{BUS}}$  short circuit the switch is expected to withstand such a condition for at least 24 hours. The SGM7228 has specially designed circuitry which prevents unintended signal bleed through as well as guaranteed system reliability during a power-down, over-voltage condition. The protection has been added to the common pins (D+, D-).

#### **Power-On Protection**

The USB 2.0 specification also notes that the USB device should be capable of withstanding a  $V_{\text{BUS}}$  short during transmission of data. This modification works by limiting current flow back into the V+ rail during the over-voltage event so current remains within the safe operating range. In this application, the switch passes the full 5.25V input signal through to the selected output, while maintaining specified off isolation on the un-selected pins.

# PACKAGE OUTLINE DIMENSIONS

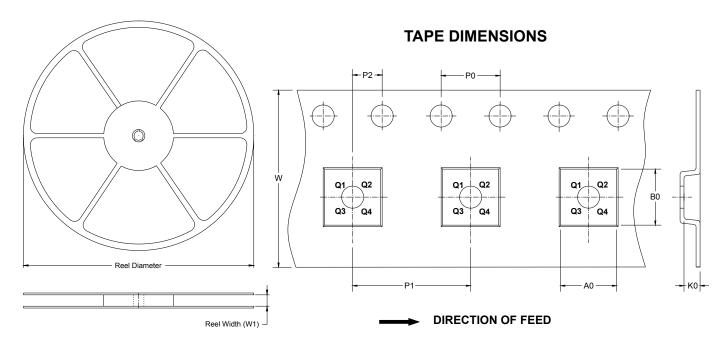
### TQFN-1.8×1.4-10L



NOTE: All linear dimensions are in millimeters.

# TAPE AND REEL INFORMATION

### **REEL DIMENSIONS**

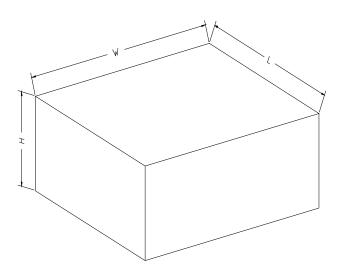


NOTE: The picture is only for reference. Please make the object as the standard.

### **KEY PARAMETER LIST OF TAPE AND REEL**

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TQFN-1.8×1.4-10L	7"	9.0	1.75	2.10	1.00	4.00	4.00	2.00	8.00	Q1

### **CARTON BOX DIMENSIONS**



NOTE: The picture is only for reference. Please make the object as the standard.

## **KEY PARAMETER LIST OF CARTON BOX**

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18